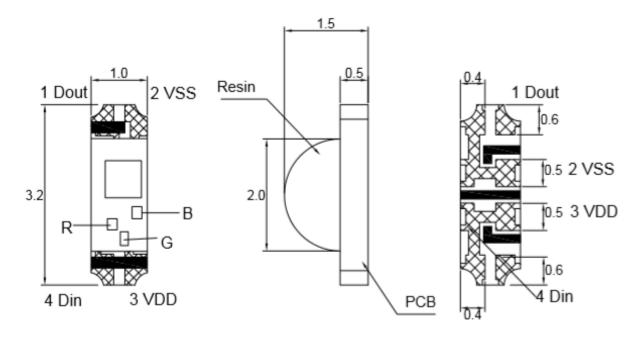


3.2 x 1.0 x 1.5mm RGB SMD LED with IC

PACKAGE DIMENSION



NO.	Symbol	Function Description
1	DOUT	Control Date Signal Output
2	VSS	Ground
3	VDD	DC Power Input
4	DIN	Control Date Signal Input

Notes

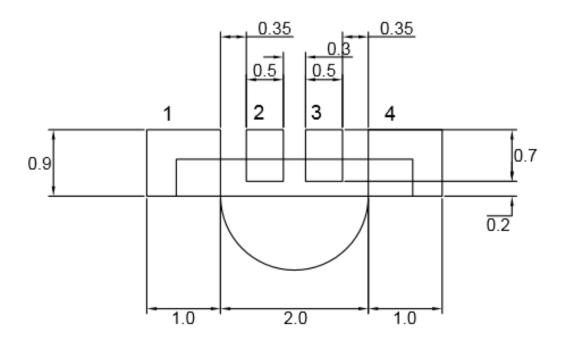
- 1. All dimensions are in millimeters; tolerance is ±0.2mm unless otherwise noted
- 2. Specifications are subject to change without notice

	Color			
Material	Emitted	Lens		
AlGalnP	Red			
InGaN	Blue	White Diffused		
InGaN	Green			



3.2 x 1.0 x 1.5mm RGB SMD LED with IC

RECOMMENDED SOLDERING PAD DIMENSIONS



Notes: The tolerances unless mentioned is ±0.1mm, Angle ±0.5. Unit=mm.



3.2 x 1.0 x 1.5mm RGB SMD LED with IC

ABSOLUTE MAXIMUM RATINGS

(Ta=25°C)

Parameter	Symbol	Rating	Unit
Supply Voltage	VDD	-0-6.0	V
LED Output Current	I _{out}	25	mA
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C
Power Dissipation	PD	400	mW

TYPICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

Dovomotov	Cymahal	Toot Condition	Rating			l lmi4	
Parameter	Symbol	Test Condition	Min.	Тур. Мах.		Unit	
Supply Voltage	VDD		3.3	5	5.5	V	
Each RGB Current	IOL	VDD=5V		5		mA	
Input High Voltage	VIH	DI	2.7		VDD	V	
Input Low Voltage	VIL	DI	0		1.0	V	
Output High Voltage	VOH	DO,@VDD=5V	4.5			1	
Output Low Voltage	VOL	DO,@VDD=5V			0.4VDD	V	
Operation Current	IDD	B,G,R no load			2	mA	
Pull Down Resistance	R _{PD}	Din, Dout(VDD=5V)		500K		Ω	

ELECTRICAL OPTICAL CHARACTERISTICS AT

(Ta=25°C)

TEED TRIBAL OF HOAL GHARAGIERRO HOU AT							
Items	S	ymbol	Min.	Тур.	Max.	Unit	Condition
Dominant Wavelength		R	-	622	1		
	λd	G	-	525	-	nm	VDD=5.0V
		В	-	470	-		
Luminous Intensity	lv	R		60			
		G		150			
		В		35			
Viewing Angle		201/2	-	120	-	deg	

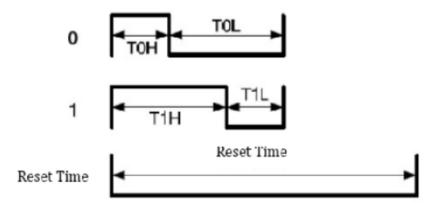
Note:

- 1. The dominant wavelength data did not including ±1 nm testing tolerance.
- 2. The luminous intensity data did not including ±15% testing tolerance.



3.2 x 1.0 x 1.5mm RGB SMD LED with IC

TIMING WAVE FORM



HIGH SPEED MODE

Item	Description	Min.	Typical	Allowance	Unit
TOH	0 code, High- level time	-	0.3	±0.15	us
TOL	0 code, Low- level time	-	0.9	±0.15	us
T1H	1 code, High- level time	-	0.9	±0.15	us
T1L	1 code, Low- level time	-	0.3	±0.15	us
Trst	Rest code, Low- level time	250			

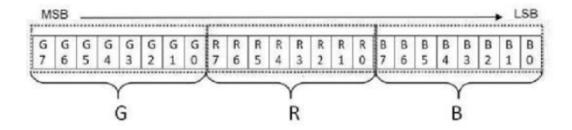
DATA COMMUNICATION

LED1	1st 24bits	2nd 24bits	3rd 24bits	4th 24bits	Trst
LED2		2nd 24bits	3rd 24bits	4th 24bits	Trst
LED3			3rd 24bits	4th 24bits	Trst
LED4				4th 24bits	Trst



3.2 x 1.0 x 1.5mm RGB SMD LED with IC

SINGAL DATA IN 24BIT FOR RGB



ADVANCE FUCNTION MODE

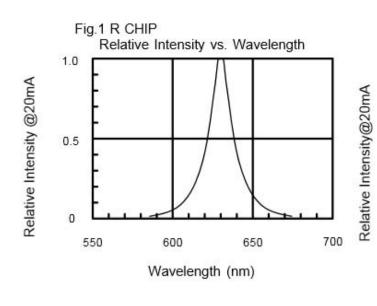
This product has a Advance Function Mode that supports the MCU to start with a specific command setting.

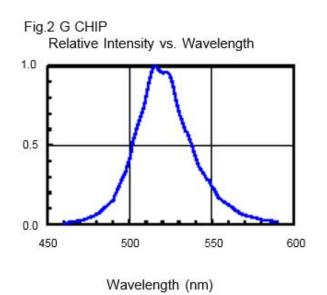
- 1. Freedback the cascaded number of LEDs and maximum sink current of R/G/B channel
- 2. Current Gain control:32 level(5bits) to adjust maximum sink current of R/G/B channel
- 3. Programmable PWM refresh rate (1.25kHz/2.5kHz/5Khz/10kHz)

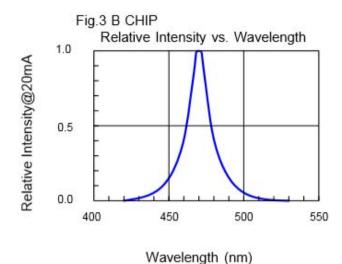


3.2 x 1.0 x 1.5mm RGB SMD LED with IC

TYPICAL ELECTRO-OPTICAL CHARACTERISTICS CURVE







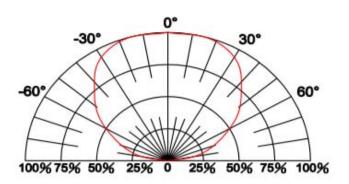
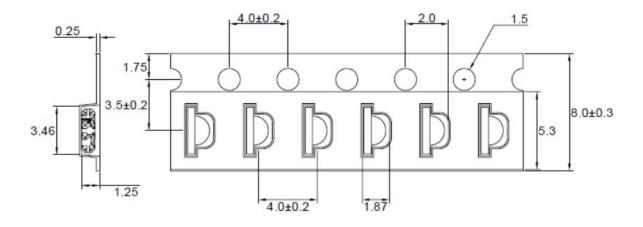


Fig.4 Directive Radiation



3.2 x 1.0 x 1.5mm RGB SMD LED with IC

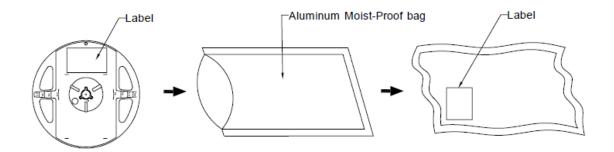
CARRIER TAPE DIMENSION



Notes:

1. Tolerance is ±0.1mm; angle is ±0.5 unless otherwise mentioned

PACKING SPECIFICATIONS



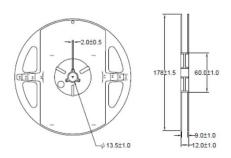
Notes:

- 1. 8.0 mm tape, 7"reel
- 2. 3000 pcs/ reel

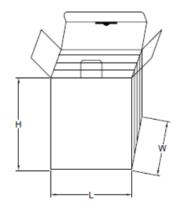


3.2 x 1.0 x 1.5mm RGB SMD LED with IC

REEL DIMENSIONS

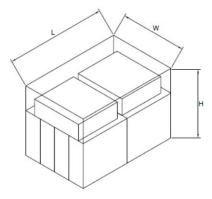


BOX EXPLANATION



Notes:

- 1. 5 BAG / INNER BOX
- 2. Inner box size: L X W X H 23cm X 8.5cm x 26cm



Notes:

- 1. 10 INNER BOXES / CARTON
- 2. Carton size: L X W X H 58cm X 34cm x 35cm



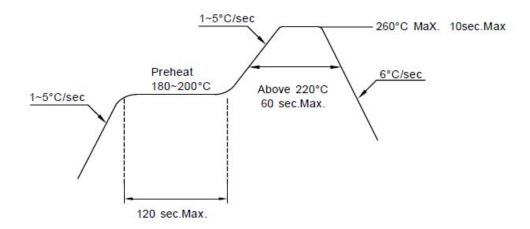
3.2 x 1.0 x 1.5mm RGB SMD LED with IC

RECOMMENDED SOLDERING CONDITION

1. Hand Solder

Basic spec is ≤280°C for 3 seconds one time only

2. PB-Free Reflow Solder



Notes:

- 1. Reflow soldering should not be done more than 2 times
- 2. When soldering, do not put stress on the LEDs during heating
- 3. After soldering, do not warp the circuit board



3.2 x 1.0 x 1.5mm RGB SMD LED with IC

PRECAUTION

Storage Time:

- 1. Calculated shelf life before opening is 12 months at <30°C and < 90% relative humidity(RH)
- 2. After bag is opened, devices which wil be subjected to reflow soldering or other high temperature processes must be
 - a. Assemebled within 168 hours in an enviornment of ≤30°C/60% RH or
 - b. Stored at ambient of 10% RH or less
- 3. Devices are required baking before assembly if:
 - a. Humidity indicator card reads >10%(for level 2a-5a) or >60%(for level 2) at ambient temperature 23±5°C
 - b. 2.a) or 2.b) doesn't meet
- 4. If baking is required, devices should be baked for >24 hours at 60±5°C/5% RH. Performing baking only once and using baked devices within 8 hours

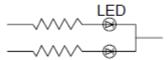
Drive method:

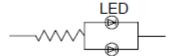
LED is a current operated device and therefore require some kind of current limiting incorporated into the

driver circuit. This current limiting typically takes the form of a current limiting resistor places in series with the LED. Consider worst csae voltage variations than could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value









- a. Recommended circuit
- b. The difference of brightness between LED could be found due to the VF-IF characteristics of LED

Cleaning:

1. Use alcohol based cleaning solvents such as isoproyl alcohol to clean the LED

Electrostatic Discharge(ESD)

 Static electricity or power surge will damage the LED. Use of a conductive wrist band or antielectrostatic glove is recommended when handling these LED. All devices, equipment and machinery must be properly grounded